

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

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LISTING OF CLAIMS:

1. (currently amended) A silicon containing curing composition comprising:

at least one silicon containing polymer selected from the group consisting of: component (A), component (B), and component (C), provided that the composition contains both the components (A) and (B) when the component (C) is absent; and

component (D) being a catalyst,

wherein,

component (A) is a silicon containing polymer, which comprises:

at least one kind of a reactive group A' selected from the group consisting of Si-R¹, Si-O-R², and Si-R³-OCOC(R⁴)=CH₂, wherein R¹ and R² each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group, R³ represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group, and R⁴ represents hydrogen or a methyl group,

an Si-O-Si bridge structure at at least one site thereof, and

20% by weight or less of a component whose weight average molecular weight is 1000 or less;

component (B) is a silicon containing polymer, which comprises:

an Si-H group,

an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less,

provided that said Si-H group is introduced into a polymer, which is formed by hydrolyzing and condensing an alkoxysilane and/or a chlorosilane, each having no Si-H group, using a reactive functional group Si-OH and/or a reactive functional group Si-Cl;

component (C) is a silicon containing polymer, which comprises:

at least one kind of a reactive group A' selected from the group consisting of Si-R¹, Si-O-R², and Si-R³-OCOC(R⁴)=CH₂, wherein R¹ and R² each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group, R³ represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group, and R⁴ represents hydrogen or a methyl group, and

an Si-H group,

an Si-O-Si bridge structure at at least one site thereof, and

20% by weight or less of a component whose weight average molecular weight is 1000 or less,

provided that said Si-H group is introduced by allowing a chlorosilane and/or a silanol, each having an Si-H group to react with an SI-OH group and/or an Si-Cl group left after a sol gel reaction of alkoxy silane and/or chlorosilane, each having no Si-H group; and

component (D) is a platinum-based catalyst.

2. (original) The silicon containing curing composition according to claim 1, wherein the total aryl group and arylene group content of the total silicon containing polymers as components (A), (B), and (C) is 0.1% to 50% by weight.

3. (previously presented) The silicon containing curing composition according to claim 1, further comprising a metal oxide fine powder as component (E).

4. (previously presented) A cured product obtained by heat curing the silicon containing curing composition according to claim 1.

5. (previously presented) The silicon containing curing composition according to claim 2, further comprising a metal oxide fine powder as component (E).